

METIS™

#### BENEFITS

- Fully-embedded lower and upper Bluetooth stack and application on a single small-size module
- Powerful on-chip CPU to run embedded customized applications
- Quick and easy implementation of Bluetooth-enabled products
- Enables smooth and rapid embedding of any 3<sup>rd</sup> party Upper Protocol Stack and profiles
- Significant time-to-market advantage via the integrated cable replacement profile and application
- On-chip USB host functionality enabling direct connectivity to computer accessories and peripherals

#### OVERVIEW

The Metis module is a generic Class1 Bluetooth module designed to provide a robust platform for rapid development of customized embedded Bluetooth applications. Metis is designed as an SMC module, with small footprint that can be easily assembled on the customer's system board. The module includes the BIC2102 application processor, Class1 Bluetooth Radio and a Flash memory to store a complete Bluetooth application solution. Metis provides a full cable replacement solution including Lower and Upper Protocol stacks, profiles and cable replacement application.

#### APPLICATIONS

- Serial-based cable replacement applications
- Customized off-the-shelf bluetooth applications
- USB-based cable replacement applications for USB Host application type including printer, digital camera, and mass-storage devices

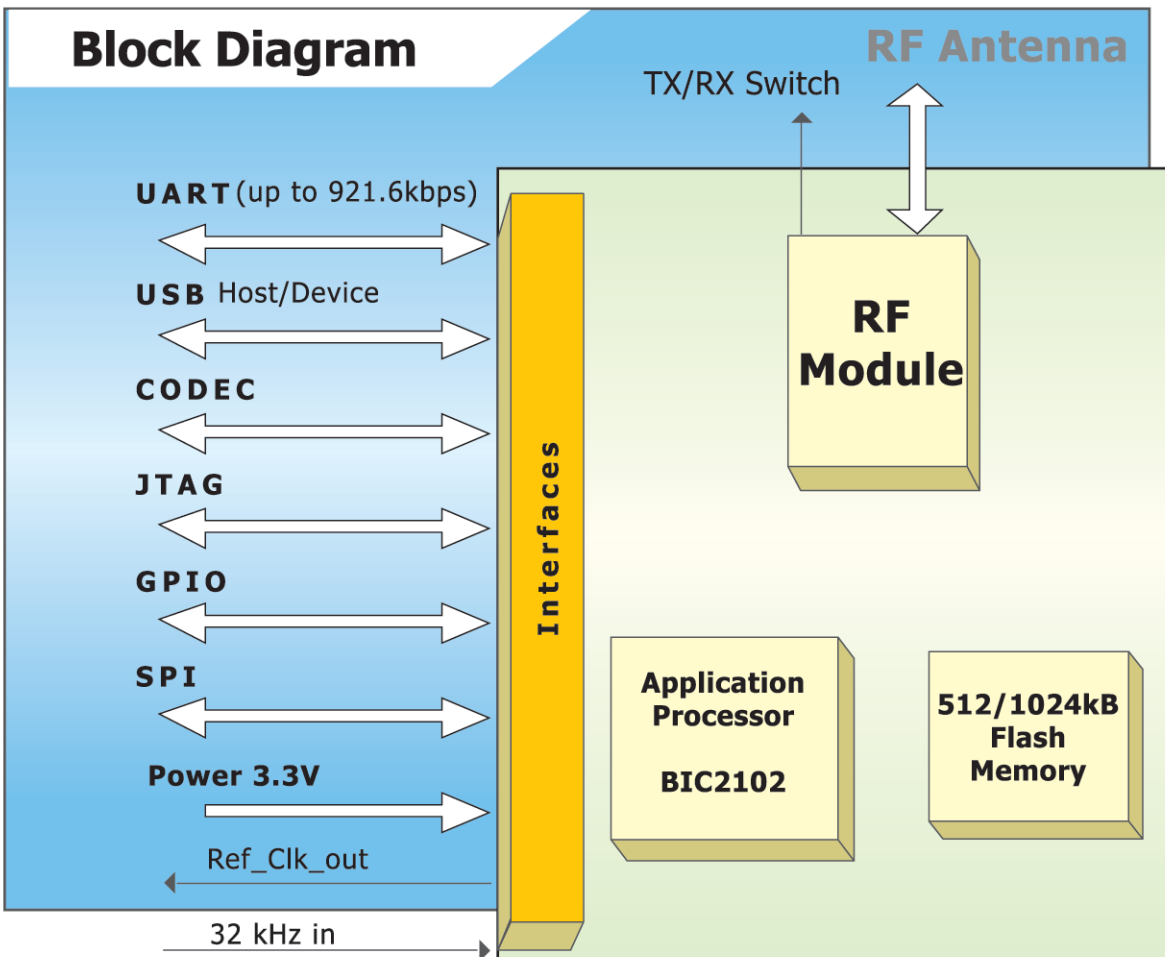
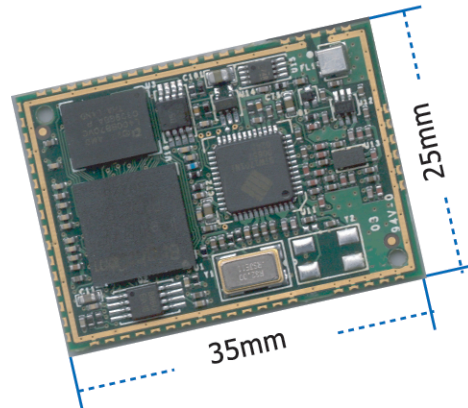
#### FEATURES

- HCI-API Lower Protocol Stack, ready for integration with embedded 3<sup>rd</sup> party Upper Protocol Stack
- Running embedded Upper Protocol Stack and Profiles (SPP, HCRP, OPP)(option)
- Point-to-point and point-to-multipoint connections (up to 7 slaves in a piconet)
- M/S switch with API support
- Supports Sniff/Hold
- Shielded RF portion
- 0.5/1MB field programmable Flash
- High-speed UART (9.6 to 921.6 Kbps), user programmable
- Full-speed USB interface V1.1 compliant (host and device)
- PCM CODEC interface (8 bit A/U-Law/13 bit Linear)
- Up to 16 programmable GPIOs
- 3 external interrupts
- RF 50ohm antenna pin for interfacing to an external antenna.
- Low power capabilities:
  - Active: 150mA max, during continuous RF TX/RX
  - Sleep: 1mA max
- Compact package size (25 x 35 x 3 mm)
- JTAG interface for flash programming and debug
- Power: 3.3V ±10%
- Operating temperature: 0-70°C
- Certifications and Approvals:
  - Bluetooth 1.1
  - Radio: ETS 300328 with test report
  - EMC: ETS 300826 with test report
  - Safety: EN 60950 with test report
- Compatible with Jupiter™ II software development platform

## BLUETOOTH CHARACTERISTICS

- Compliant to Bluetooth specifications v1.1
- Air interface data speed: up to 600kbps
- Bluetooth Class 1 Radio circuitry

## MECHANICAL DIMENSIONS



For more information, please visit our website at [www.flextronics.com/wireless](http://www.flextronics.com/wireless) or contact us at [Bluetooth@flextronics.com](mailto:Bluetooth@flextronics.com). Flextronics is an associate member of the US-based Bluetooth Special Interest Group (SIG).